TEXAS INSTRUMENTS

Bill of Materials

TI DESIGNS

TIDM-1021

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint	Note
1	1	PCB		Printed Circuit Board	Any	TIDM-1021		
2	12	B1, B2, B3, B4, B5, B6, B7, B8, B9, B10, B11, B12		Mutual RX Electrode		CAP_RX		
3	12	D0, D1, D2, D3, D4, D5, D6, D7, D8, D9, D10, D11		LED, Red, SMD, Reverse Mount, 1206	Dialight	597-6001-607F	1206	
4	1	J2		Socket Strip, Surface Mount, Double Row ,0.100" Pitch, 16 PINS.	SAMTEC			
5	1	LS1		Magnetic Transducer, SMD	Sobertron	ST-03BL	8.5x8.5mm	
6	1	U1		MSP430 Captivate Microcontroller	Texas Instruments	MSP430FR2633IDA	DA (32 TSSOP)	
7	1	C3	0.1uF	CAP, CERM, 0.1 µF, 16 V, +/- 10%, X7R, 0402	Wurth Elektronik	885012205037	0402	
8	1	C4	1uF	CAP, CERM, 1 µF, 10 V, +/- 10%, X5R, 0603	MuRata	GRM188R61A105KA61D	0603	
9	1	C5	1000pF	CAP, CERM, 1000 pF, 50 V, +/- 10%, X5R, 0402	MuRata	GRM155R61H102KA01D	0402	
10	1	C6	4.7uF	CAP, CERM, 4.7 µF, 10 V, +/- 20%, X6S, 0603	MuRata	GRM185C81A475ME11D	0603	
11	1	C8	0.1uF	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X5R, 0603	TDK	C1608X5R1H104K080AA	0603	
12	12	CE1, CE2, CE3, CE4, CE5, CE6, CE7, CE8, CE9, CE10, CE11, CE12	68pF	CAP, CERM, 68 pF, 50 V, +/- 5%, C0G/NP0, 0402	TDK	C1005C0G1H680J050BA	0402	
13	1	Q1	50V	MOSFET, N-CH, 50 V, 0.22 A, SOT-23	Fairchild Semiconductor	BSS138	SOT-23	
14	1	R5	47k	RES, 47k ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW040247K0JNED	0402	
15	1	R20	50	RES, 50, 1%, 0.1 W, 0603	Vishay-Dale	CRCW060350R0FKEA	0603	
16	1	R21	180	RES, 180, 5%, 0.063 W, AEC-Q200 Grade 0, 0402	Vishay-Dale	CRCW0402180RJNED	0402	
17	1	R22	11k	RES, 11 k, 5%, 0.063 W, AEC-Q200 Grade 0, 0402	Vishay-Dale	CRCW040211K0JNED	0402	
18	12	RE1, RE2, RE3, RE4, RE5, RE6, RE7, RE8, RE9, RE10, RE11, RE12	470	RES, 470, 5%, 0.063 W, AEC-Q200 Grade 0, 0402	Vishay-Dale	CRCW0402470RJNED	0402	
19	12	RL0, RL1, RL2, RL3, RL4, RL5, RL6, RL7, RL8, RL9, RL10, RL11	330	RES, 330, 5%, 0.063 W, AEC-Q200 Grade 0, 0402	Vishay-Dale	CRCW0402330RJNED	0402	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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